



Title of Change:	Mold compound change due to End of Life of Samsung SDI molding compound – Batch 6	
Proposed First Ship date:	4 January 2020	
Contact Information:	Contact your local ON Semiconductor Sales Office or < PCN.Support@onsemi.com >	
Samples:	Samples should be available after completion of qualification. Contact your local ON Semiconductor Sales Office or < PCN.Samples@onsemi.com > Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.	
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact < PCN.Support@onsemi.com >	
Change Part Identification:	Product with date code 2001 or newer will be assembled with a new mold compound.	
Change Category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____	
Change Sub-Category(s):	<input type="checkbox"/> Manufacturing Site Addition <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Site Transfer <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Other: _____	
Sites Affected:	ON Semiconductor Sites: ON Semiconductor Suzhou	External Foundry/Subcon Sites: TFME Shantou Huashan Electronic Devices SP Semiconductor and Communications

**Description and Purpose:**

ON Semiconductor would like to inform its customers of a change in the mold compound for the devices listed in this IPCN. This change is a result of an end of life notification received for Samsung SDI EMC. The replacement mold compound is still being decided for many packages and will be declared on the Final Product Change Notification, which will be sent out 97 days prior to its implementation.

	Before Change Description	After Change Description
Mold Compound (TO220F-4 Package)	Samsung ST-7100HS	TBD
Mold Compound (TO220-2 Package)	Samsung SL7300HFM/SI7200DX2/SG8200DL/SG8300HK	TBD
Mold Compound (TO220F-3 Package)	Samsung SL7300HFM/SI7200DX2/SG8200DL/SG8300HK	TBD
Mold Compound (TO3P-5 Package)	Samsung SI7200DX2	TBD
Mold Compound (TO3P-3 Package)	Samsung SL7300HXM/SI7200DX2/SG8200DL	TBD
Mold Compound (TO264-3 Package)	Samsung SL7300HFM	TBD
Mold Compound (TO247-2 Package)	Samsung SG8200DL/SL7300HFM	TBD
Mold Compound (TO247-3 Package)	Samsung SG8200DL/SL7300HFM	TBD
Mold Compound (TP247-3 Package)	Samsung SG8200DL	TBD
Mold Compound (TP247-4 Package)	Samsung SG8200DL/SL7300HFM	TBD
Mold Compound (D2PAK-3 Package)	Samsung SG8200DL	Sumitomo EME-G700HF
Mold Compound (SPM5 Package)	Samsung SL7300HW	KCC KTMC3100GP3
Mold Compound (SPM3 Package)	Samsung SL7300HW	TBD

The qualifications will be completed as quickly as possible, but due to the number of qualifications being performed, multiple Final Product Change Notifications (FPCNs) will be released to customers as the various packages/locations are qualified.

There is no product marking change as a result of this change.

**Qualification Plan:**

All Packages will follow the generic plans shown below based on Package type and application:

IC non-auto:

Test	Specification	Condition	Interval
HTOL	JESD22-A108	Ta= TBD °C, 100 % max rated Vcc	1008 hrs
HTSL	JESD22-A103	Ta= max Tj stg °C	1008 hrs
TC	JESD22-A104	Ta= - 65°C to +150°C	1000 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
PC	J-STD-020 JESD-A113	MSL _____ @ _____ °C (per datasheet as required)	
RSH	JESD22- B106	Ta = 265C, 10 sec	
SD	JSTD002	Ta = 245C, 10 sec	

Discrete non-auto:

Test	Specification	Condition	Interval
HTRB	JESD22-A108	Ta= max Tj°C, 80% max rated V	1008 hrs
HTGB	JESD22-A108	Ta= max Tj°C, 100% max rated Vgss (tech specific)	1008 hrs
HTSL	JESD22-A103	Ta= max Tj stg	1008 hrs
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = TBD by pkg min	TBD cyc determined by pkg
TC	JESD22-A104	Ta= - 65°C to +150°C	1000 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
PC	J-STD-020 JESD-A113	MSL _____ @ _____ °C as required by MSL level on datasheet (SMT)	
RSH	JESD22- B106	Ta = 265C, 10 sec	
SD	JSTD002	Ta = 245C, 10 sec	

Estimated date for qualification completion: 30 August 2019 For first packages with additional qualifications after this date.

**List of Affected Parts:**

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
BYV32-200G	MUR8100EG
BYW29-200G	MUR8100EG
BYW51-200G	MUR8100EG
BYW80-200G	MUR8100EG
FFA60UP30DNTU	FQA11N90-F109, RHRG3060CC, RHRG75120
FFAF30UA60S	FFAF60UA60DN
FFAF60UA60DN	RURP15100-F085P, RHRG75120, FFAF60UA60DN
FFH30S60STU	RURP15100-F085P, RHRG75120
FFH30US30DN	RURP15100-F085P, RHRG75120
FFH50US60S	RURP15100-F085P, RHRG75120
FFH60UP40S	RURP15100-F085P, RHRG75120
FFH60UP40S3	RURP15100-F085P, RHRG75120
FFH60UP60S	RURP15100-F085P, RHRG75120
FFP08D60L2	RURP15100-F085P, RHRG75120
FFP08S60SNTU	RURP15100-F085P, RHRG75120
FFP15S60STU	RURP15100-F085P, RHRG75120
FFP30S60STU	RURP15100-F085P, RHRG75120
FFPF08H60STU	RURP15100-F085P, RHRG75120
FFPF08S60SNTU	RURP15100-F085P, RHRG75120
FFPF08S60STU	RURP15100-F085P, RHRG75120
FFPF10UA60ST	RURP15100-F085P, RHRG75120
FFPF15S60STU	RURP15100-F085P, RHRG75120
FFPF20UA60DN	RURP15100-F085P, RHRG75120
FFPF20UP40S	RURP15100-F085P, RHRG75120
FFPF20UP60DNTU-G	RURP15100-F085P, RHRG75120
FYP1010DNTU	FYP2010DNTU
FYP2006DNTU	FYP2010DNTU
FYP2010DNTU	FYP2010DNTU
ISL9K1560G3	RHRG75120, RHRG3060CC
ISL9K3060G3	RURP15100-F085P, RHRG75120
ISL9K460P3	RURP15100-F085P, RHRG75120
ISL9R1560G2	RURP15100-F085P, RHRG75120
ISL9R1560P2	RURP15100-F085P, RHRG75120



ISL9R18120G2	RHRG75120, RHRG3060CC
ISL9R30120G2	RURP15100-F085P, RHRG75120
ISL9R3060G2	RHRG75120, RHRG3060CC
ISL9R3060P2	RURP15100-F085P, RHRG75120
ISL9R860P2	RURP15100-F085P, RHRG75120
MBR10100G	MBR60L45CTG
MBR1035G	MBR60L45CTG
MBR1045G	MBR60L45CTG
MBR1060G	MBR60L45CTG
MBR1080G	MBR60L45CTG
MBR1090G	MBR60L45CTG
MBR10L60CTG	MBR60L45CTG
MBR1535CTG	MBR60L45CTG
MBR1545CTG	MBR60L45CTG
MBR16100CTG	MBR60L45CTG
MBR1635G	MBR60L45CTG
MBR1645G	MBR60L45CTG
MBR20200CTG	MBR60L45CTG
MBR2030CTLG	MBR60L45CTG
MBR2060CTG	MBR60L45CTG
MBR2080CTG	MBR60L45CTG
MBR2090CTG	MBR60L45CTG
MBR20H150CTG	MBR60L45CTG
MBR20L60CTG	MBR60L45CTG
MBR2515LG	MBR60L45CTG
MBR2535CTG	MBR60L45CTG
MBR2535CTLG	MBR60L45CTG
MBR2545CTG	MBR60L45CTG
MBR30H100CTG	MBR60L45CTG
MBR30H30CTG	MBR60L45CTG
MBR30L60CTG	MBR60L45CTG
MBR4015CTLG	MBR60L45CTG
MBR40250G	MBR60L45CTG
MBR40250TG	MBR60L45CTG
MBR40L45CTG	MBR60L45CTG
MBR40L60CTG	MBR60L45CTG
MBR41H100CTG	MBR60L45CTG
MBR60H100CTG	MBR60L45CTG



Initial Product/Process Change Notification

Document # : IPCN22647XE

Issue Date: 9 April 2019

MBR60L45CTG	MBR60L45CTG
MBR735G	MBR60L45CTG
MBRP1545NTU	FYP2010DNTU
MBRP2045NTU	FYP2010DNTU
MBRP3010NTU	FQP12N60C, FYP2010DNTU
MBRP3045NTU	FYP2010DNTU
RHRG1560CC	RHRG75120, RHRG3060CC
RHRG30120	RHRG75120, RHRG3060CC
RHRG3060	RHRG75120, RHRG3060CC
RHRG3060CC	RHRG75120, RHRG3060CC
RHRG5060	RHRG75120, RHRG3060CC
RHRG75120	RURP15100-F085P, RHRG75120
RHRP15120	RURP15100-F085P, RHRG75120
RHRP15120-F102	RURP15100-F085P, RHRG75120
RHRP1560	RURP15100-F085P, RHRG75120
RHRP1560-F102	RURP15100-F085P, RHRG75120
RHRP30120	RURP15100-F085P, RHRG75120
RHRP30120-F102	RURP15100-F085P, RHRG75120
RHRP3060	RURP15100-F085P, RHRG75120
RHRP3060-F102	RURP15100-F085P, RHRG75120
RHRP8120	RURP15100-F085P, RHRG75120
RHRP8120-F102	RURP15100-F085P, RHRG75120
RHRP860	RURP15100-F085P, RHRG75120
RHRP860-F102	RURP15100-F085P, RHRG75120
RURG1520CC	RURP15100-F085P, RHRG75120
RURG3020CC	RHRG75120, RHRG3060CC
RURG3060	RURP15100-F085P, RHRG75120
RURG3060CC	RHRG75120, RHRG3060CC
RURG5060	RHRG75120, RHRG3060CC
RURG80100	RURP15100-F085P, RHRG75120
RURG8060	RURP15100-F085P, RHRG75120
RURP1560	RURP15100-F085P, RHRG75120
RURP3060	RURP15100-F085P, RHRG75120
RURP8100	RURP15100-F085P, RHRG75120
RURP860	RURP15100-F085P, RHRG75120

Japanese translation of the notification starts here.
通知の日本語訳はここから始まります。

Note: The Japanese version is for reference only. In case of any differences between the English and Japanese version, the English version shall control.

注：日本語版は参照用です。英語版と日本語版の違いがある場合は、英語版が優先されます。



最終製品 / プロセス変更通知

文書番号# : IPCN22647XE

発行日 : 9 April 2019

変更件名:	Samsung SDI 製モールドコンパウンド - Batch 6 の生産終了に伴うモールドコンパウンドの変更	
初回出荷予定日:	4 January 2020	
連絡先情報:	現地のオン・セミコンダクター営業所または < PCN.Support@onsemi.com > にお問い合わせください。	
サンプル:	サンプルは認定完了後に提供が可能となります。 現地のオン・セミコンダクター営業所または < PCN.Samples@onsemi.com > にお問い合わせください。 サンプルは、この変更の初回通知、初回 PCN の日付から 30 日以内に要求してください。	
通知種別:	これは、お客様宛の初回製品 / プロセス変更通知 (IPCN) です。IPCN は、近日中に実施される変更に関する事前通知であり、変更の詳細および影響を受けるデバイスについての一般情報が記載されます。また、暫定的な信頼性認証計画も記載されます。 最終的な認定データおよび特性データは最終製品 / プロセス変更通知 (FPCN) に含まれます。この IPCN は、変更実施から少なくとも 90 日前に発行される最終製品 / プロセス変更通知 (FPCN) に先だって通知されます。ご不明な点がありましたら、< PCN.Support@onsemi.com > にお問い合わせください。	
変更部品の識別:	日付コード 2001 以降の製品は、新しいモールドコンパウンドで組み立てられます	
変更カテゴリ:	<input type="checkbox"/> ウェハファブの変更 <input checked="" type="checkbox"/> アセンブリの変更 <input type="checkbox"/> 試験の変更 <input type="checkbox"/> その他 _____	
変更サブカテゴリ:	<input type="checkbox"/> 製造拠点の追加 <input checked="" type="checkbox"/> 材料の変更 <input type="checkbox"/> データシート/製品資料の変更 <input type="checkbox"/> 製造拠点の移転 <input type="checkbox"/> 製品仕様の変更 <input type="checkbox"/> 出荷/パッケージング/表記 <input type="checkbox"/> 製造プロセスの変更 <input type="checkbox"/> その他: _____	
影響を受ける拠点:	オン・セミコンダクター拠点: ON Semiconductor Suzhou	外部製造工場 / 下請業者拠点: TFME Shantou Huashan Electronic Devices SP Semiconductor and Communications



説明および目的:

オン・セミコンダクターは、本 IPCN に列記されたデバイスに対するモールドコンパウンドの変更をお客様にお知らせいたします。この変更は、SDI EMC から受けた生産終了の通知によるものです。代替のモールドコンパウンドは、多くのパッケージ用に使用すると決定されているもので、実施の 97 日前までに送付される最終製品変更通知にて公表されます。

	変更前の表記	変更後の表記
モールド・コンパウンド (TO220F-4 パッケージ)	Samsung ST-7100HS	TBD
モールド・コンパウンド (TO220-2 パッケージ)	Samsung SL7300HFM/SI7200DX2/SG8200DL/SG8300HK	TBD
モールド・コンパウンド (TO220F-3 パッケージ)	Samsung SL7300HFM/SI7200DX2/SG8200DL/SG8300HK	TBD
モールド・コンパウンド (TO3P-5 パッケージ)	Samsung SI7200DX2	TBD
モールド・コンパウンド (TO3P-3 パッケージ)	Samsung SL7300HXM/SI7200DX2/SG8200DL	TBD
モールド・コンパウンド (TO264-3 パッケージ)	Samsung SL7300HFM	TBD
モールド・コンパウンド (TO247-2 パッケージ)	Samsung SG8200DL/SL7300HFM	TBD
モールド・コンパウンド (TO247-3 パッケージ)	Samsung SG8200DL/SL7300HFM	TBD
モールド・コンパウンド (TP247-3 パッケージ)	Samsung SG8200DL	TBD
モールド・コンパウンド (TP247-4 パッケージ)	Samsung SG8200DL/SL7300HFM	TBD
モールド・コンパウンド (D2PAK-3 パッケージ)	Samsung SG8200DL	Sumitomo EME-G700HF
モールド・コンパウンド (SPM5 パッケージ)	Samsung SL7300HW	KCC KTMC3100GP3
モールド・コンパウンド (SPM3 パッケージ)	Samsung SL7300HW	TBD

認定に関してはできる限り早急に終了する予定ですが、各種パッケージ/場所が認定されることになり、実施される認定が多数になるため、複数の最終製品変更通知 (FPCNs) がお客様に発行されることとなります。

今回の変更に伴う製品表示の変更はありません。



認定計画:

すべてのパッケージは、パッケージタイプおよび適用に基づき以下に示す一般計画に従います。

IC 非自動:

テスト	仕様	条件	間隔
HTOL	JESD22-A108	Ta= TBD °C, 100 % max rated Vcc	1008 hrs
HTSL	JESD22-A103	Ta= max Tj stg °C	1008 hrs
TC	JESD22-A104	Ta= - 65°C to +150°C	1000 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
PC	J-STD-020 JESD-A113	MSL _____ @ _____ °C (per datasheet as required)	
RSH	JESD22- B106	Ta = 265C, 10 sec	
SD	JSTD002	Ta = 245C, 10 sec	

ディスクリート非自動:

テスト	仕様	条件	間隔
HTRB	JESD22-A108	Ta= max Tj°C, 80% max rated V	1008 hrs
HTGB	JESD22-A108	Ta= max Tj°C, 100% max rated Vgss (tech specific)	1008 hrs
HTSL	JESD22-A103	Ta= max Tj stg	1008 hrs
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = TBD by pkg min	TBD cyc determined by pkg
TC	JESD22-A104	Ta= - 65°C to +150°C	1000 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
PC	J-STD-020 JESD-A113	MSL _____ @ _____ °C as required by MSL level on datasheet (SMT)	
RSH	JESD22- B106	Ta = 265C, 10 sec	
SD	JSTD002	Ta = 245C, 10 sec	

認定完了予定日: 2019年8月30日この日付以降の追加認定に基づく初期パッケージに関して。



影響を受ける部品の一覧:

注: 部品一覧には標準部品番号 (既製品) のみが記載されています。本 PCN の影響を受けるカスタム部品番号は、PCN メールで提供される顧客個別の付録、または PCN カスタマイズポータルに記載されています。

部品番号	認定試験用ピークル
BYV32-200G	MUR8100EG
BYW29-200G	MUR8100EG
BYW51-200G	MUR8100EG
BYW80-200G	MUR8100EG
FFA60UP30DNTU	FQA11N90-F109, RHRG3060CC, RHRG75120
FFAF30UA60S	FFAF60UA60DN
FFAF60UA60DN	RURP15100-F085P, RHRG75120, FFAF60UA60DN
FFH30S60STU	RURP15100-F085P, RHRG75120
FFH30US30DN	RURP15100-F085P, RHRG75120
FFH50US60S	RURP15100-F085P, RHRG75120
FFH60UP40S	RURP15100-F085P, RHRG75120
FFH60UP40S3	RURP15100-F085P, RHRG75120
FFH60UP60S	RURP15100-F085P, RHRG75120
FFP08D60L2	RURP15100-F085P, RHRG75120
FFP08S60SNTU	RURP15100-F085P, RHRG75120
FFP15S60STU	RURP15100-F085P, RHRG75120
FFP30S60STU	RURP15100-F085P, RHRG75120
FFPF08H60STU	RURP15100-F085P, RHRG75120
FFPF08S60SNTU	RURP15100-F085P, RHRG75120
FFPF08S60STU	RURP15100-F085P, RHRG75120
FFPF10UA60ST	RURP15100-F085P, RHRG75120
FFPF15S60STU	RURP15100-F085P, RHRG75120
FFPF20UA60DN	RURP15100-F085P, RHRG75120
FFPF20UP40S	RURP15100-F085P, RHRG75120
FFPF20UP60DNTU-G	RURP15100-F085P, RHRG75120
FYP1010DNTU	FYP2010DNTU
FYP2006DNTU	FYP2010DNTU
FYP2010DNTU	FYP2010DNTU
ISL9K1560G3	RHRG75120, RHRG3060CC
ISL9K3060G3	RURP15100-F085P, RHRG75120
ISL9K460P3	RURP15100-F085P, RHRG75120
ISL9R1560G2	RURP15100-F085P, RHRG75120
ISL9R1560P2	RURP15100-F085P, RHRG75120



ISL9R18120G2	RHRG75120, RHRG3060CC
ISL9R30120G2	RURP15100-F085P, RHRG75120
ISL9R3060G2	RHRG75120, RHRG3060CC
ISL9R3060P2	RURP15100-F085P, RHRG75120
ISL9R860P2	RURP15100-F085P, RHRG75120
MBR10100G	MBR60L45CTG
MBR1035G	MBR60L45CTG
MBR1045G	MBR60L45CTG
MBR1060G	MBR60L45CTG
MBR1080G	MBR60L45CTG
MBR1090G	MBR60L45CTG
MBR10L60CTG	MBR60L45CTG
MBR1535CTG	MBR60L45CTG
MBR1545CTG	MBR60L45CTG
MBR16100CTG	MBR60L45CTG
MBR1635G	MBR60L45CTG
MBR1645G	MBR60L45CTG
MBR20200CTG	MBR60L45CTG
MBR2030CTLG	MBR60L45CTG
MBR2060CTG	MBR60L45CTG
MBR2080CTG	MBR60L45CTG
MBR2090CTG	MBR60L45CTG
MBR20H150CTG	MBR60L45CTG
MBR20L60CTG	MBR60L45CTG
MBR2515LG	MBR60L45CTG
MBR2535CTG	MBR60L45CTG
MBR2535CTLG	MBR60L45CTG
MBR2545CTG	MBR60L45CTG
MBR30H100CTG	MBR60L45CTG
MBR30H30CTG	MBR60L45CTG
MBR30L60CTG	MBR60L45CTG
MBR4015CTLG	MBR60L45CTG
MBR40250G	MBR60L45CTG
MBR40250TG	MBR60L45CTG
MBR40L45CTG	MBR60L45CTG
MBR40L60CTG	MBR60L45CTG
MBR41H100CTG	MBR60L45CTG
MBR60H100CTG	MBR60L45CTG



MBR60L45CTG	MBR60L45CTG
MBR735G	MBR60L45CTG
MBRP1545NTU	FYP2010DNTU
MBRP2045NTU	FYP2010DNTU
MBRP3010NTU	FQP12N60C, FYP2010DNTU
MBRP3045NTU	FYP2010DNTU
RHRG1560CC	RHRG75120, RHRG3060CC
RHRG30120	RHRG75120, RHRG3060CC
RHRG3060	RHRG75120, RHRG3060CC
RHRG3060CC	RHRG75120, RHRG3060CC
RHRG5060	RHRG75120, RHRG3060CC
RHRG75120	RURP15100-F085P, RHRG75120
RHRP15120	RURP15100-F085P, RHRG75120
RHRP15120-F102	RURP15100-F085P, RHRG75120
RHRP1560	RURP15100-F085P, RHRG75120
RHRP1560-F102	RURP15100-F085P, RHRG75120
RHRP30120	RURP15100-F085P, RHRG75120
RHRP30120-F102	RURP15100-F085P, RHRG75120
RHRP3060	RURP15100-F085P, RHRG75120
RHRP3060-F102	RURP15100-F085P, RHRG75120
RHRP8120	RURP15100-F085P, RHRG75120
RHRP8120-F102	RURP15100-F085P, RHRG75120
RHRP860	RURP15100-F085P, RHRG75120
RHRP860-F102	RURP15100-F085P, RHRG75120
RURG1520CC	RURP15100-F085P, RHRG75120
RURG3020CC	RHRG75120, RHRG3060CC
RURG3060	RURP15100-F085P, RHRG75120
RURG3060CC	RHRG75120, RHRG3060CC
RURG5060	RHRG75120, RHRG3060CC
RURG80100	RURP15100-F085P, RHRG75120
RURG8060	RURP15100-F085P, RHRG75120
RURP1560	RURP15100-F085P, RHRG75120
RURP3060	RURP15100-F085P, RHRG75120
RURP8100	RURP15100-F085P, RHRG75120
RURP860	RURP15100-F085P, RHRG75120